

IN THE SPECIFICATION:

Please replace paragraph number [0001] with the following rewritten paragraph:

[0001] This application is a continuation of application Serial No. 10/077,451, filed February 14, 2002, ~~pending~~ now U.S. Patent 6,583,504, issued June 24, 2003, which is a continuation of application Serial No. 09/837,038, filed April 18, 2001, now U.S. Patent 6,373,132 B2, issued April 16, 2002, which is a continuation of application Serial No. 09/302,343, filed April 29, 1999, now U.S. Patent 6,249,050 B1, issued June 19, 2001, which is a continuation of application Serial No. 08/909,228, filed August 11, 1997, now U.S. Patent 5,959,349, issued September 28, 1999, which is a divisional of application Serial No. 08/804,911, filed February 25, 1997, now U.S. Patent 6,001,672, issued December 14, 1999.

Please replace paragraph number [0027] with the following rewritten paragraph:

[0027] In operation, a heated pellet of resin mold compound 30 is disposed beneath ram or plunger 32 in pot 34. The plunger descends, melting the pellet and forcing the melted encapsulant down through sprue 36 and into primary runner 38, from and through the mold cavities 44 through the short side thereof flowing across the semiconductor device assemblies 100, wherein semiconductor device assemblies 100 comprising semiconductor devices 102 with attached lead frames 104 are disposed (usually in strips so that a strip of six lead frames, for example, would be cut and placed in and across the six cavities 44 shown in FIG. 3). Air in the runners 42 (see FIG. 3) and 40 and mold cavities 44 is vented to the atmosphere through vents 46 and 48. At the end of the molding operation, the encapsulant is "packed" by application of a high pressure to eliminate voids and reduce non-uniformities of the encapsulant in the mold cavities 44. After molding, the encapsulated semiconductor device assemblies 100 are ejected from the cavities 44 by ejector pins 50, after which they are ~~post-~~ post-cured at an elevated temperature to complete cross-linking of the resin, followed by other operations as known in the art and set forth in FIG. 1, by way of example. It will be appreciated that other transfer molding apparatus configurations, as well as variations in the details of the

described method are known in the art. However, none of such are pertinent to the invention, and so will not be discussed herein.